

# 应用于高纵横比线路板上之高性能脉冲电镀铜

## High Performance PPR Copper Plating for HAR Boards



### COPPER GLEAM™ PPR-II Acid Copper

COPPER GLEAM™ PPR-II Acid Copper is specially designed for plating through hole in high aspect ratio boards, working with soluble anodes and simple waveform in vertical application.

COPPER GLEAM™ PPR-II 专门设计应用于高纵横比之线路板，适用于垂直线可溶性及不溶性阳极，且可透过简易的波形进行操控。

#### Features and Benefits 特长及优点

- Perform high throwing power for through hole in high aspect ratio of thick board  
于高纵横比之厚板中，具有高通孔深镀能力之表现
- With outstanding bath stability and easy to restart after idling  
具优越的槽液稳定性及閒置后仅须短时间的预镀
- Offer excellent thermal reliability  
提供优越的热信赖度

#### Outstanding throwing power performance 优越的通孔深镀能力



#### Aged bath with consistent TP% performance 于老化槽液仍有稳定的深镀能力

